



TFW

**TRANSMITTAL LETTER
(General - Patent Pending)**Docket No.
END920010135US2

In Re Application Of: Alcoe et al.

Application No. 10/665,669	Filing Date 9/18/2003	Examiner Thao X. Le	Customer No. 30449	Group Art Unit 2814	Confirmation No.
-------------------------------	--------------------------	------------------------	-----------------------	------------------------	------------------

Title: THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES

COMMISSIONER FOR PATENTS:

Transmitted herewith is:

Request for Reconsideration (14 pages)**Replacement Sheet (Fig. 6)**

in the above identified application.

- No additional fee is required.
- A check in the amount of _____ is attached.
- The Director is hereby authorized to charge and credit Deposit Account No. 09-0457(IBM) as described below.
 - Charge the amount of _____
 - Credit any overpayment.
 - Charge any additional fee required.
- Payment by credit card. Form PTO-2038 is attached.

WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.

Signature

Dated: 01/25/2005

Jack P. Friedman

Reg. No. 44,688

Schmeiser, Olsen & Watts
3 Lear Jet Lane, Suite 201
Latham, NY 12110
(518) 220-1850

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on

1/25/05

(Date)

Signature of Person Mailing Correspondence

cc:

Kim Dwileski

Typed or Printed Name of Person Mailing Correspondence